Abstracts

Low Cost to Packages for High Speed/Microwave Applications

D.A. Larson, D.E. Heckaman, J.A. Frisco and D.A. Haskins. "Low Cost to Packages for High Speed/Microwave Applications." 1986 MTT-S International Microwave Symposium Digest 86.1 (1986 [MWSYM]): 437-440.

A set of low cost, microwave quality packages has been developed for use with both monolithic and hybrid integrated circuits. The packages are modeled after the common TO-style packages, thus allowing the use of an established, cost effective manufacturing base. They are plug-in packages, with pins on 0.100 inch spacings for easy insertion at higher levels. Test results of the TO-8 style package show better than 20 dB return loss through 15 GHz. Isolation between adjacent ports is greater than 50 dB. With package size varying from the small 0.300 inch diameter TO-5 can to the 1.000 inch diameter TO-3 can, applications requiring one GaAs chip, several cascaded chips, or an entire hybrid substrate can be accommodated. The low cost, high performance attributes of these packages make them ideal for high speed, high frequency subsystems.

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